

特徴 Feature

● 低伝送損失化

誘電率 (Low-Dk) / 低誘電正接 (Low-Df) 基材を採用し
アンテナ特性、信号品質の向上を実現します
Low⁺ロッド銅箔も採用し、導体損失も低減します

● 新工法の採用 (MSAP : Modified Semi-Additive Process)

回路形成後に要求形状を再現し、アンテナ特性、信号品質の
向上を実現し、Zo、Zdifコントロールに対応します

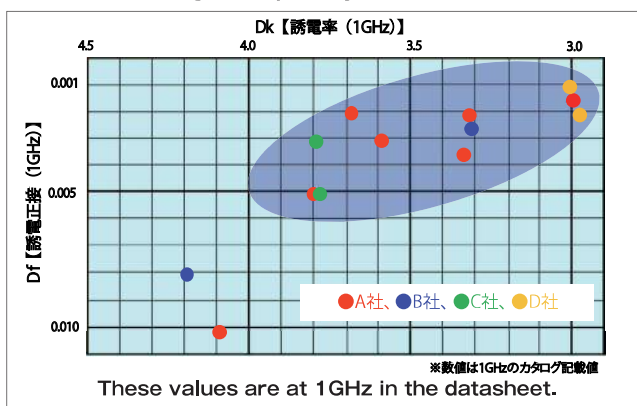
● Lower Transmission Loss

Antenna property and signal quality have been improved
by using low-Dk, low-Df materials.

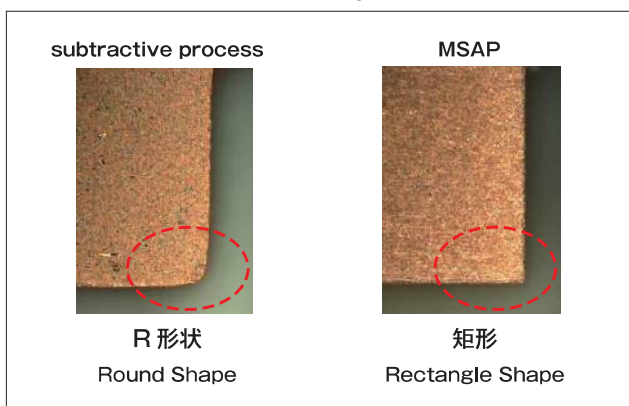
● New Process (MSAP: Modified Semi-Additive Process)

Installed new process have completed circuit pattern requested,
and Antenna property and signal quality have been improved.
This process is more suitable for Zo, Zdif control.

High frequency material



Process comparison

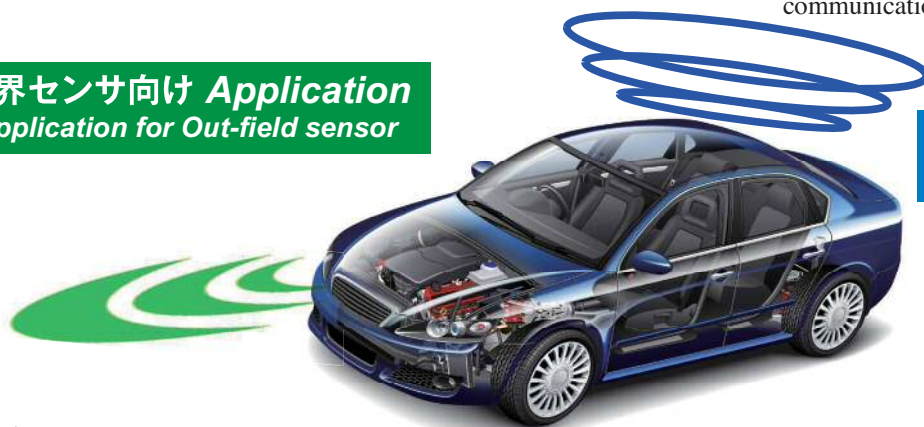


用途 Application

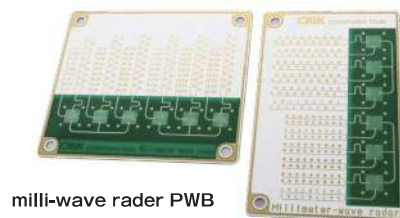
- ADAS・自動運転 (ミリ波レーダー、レーザーレーダー)
- 運行支援・通信システム

- ADAS, Autonomous (milli-wave rader, LiDAR)
- Driving assist, Communication system (Automotive communication, 5G communication)

外界センサ向け Application
Application for Out-field sensor



運行支援・通信システム
Driving assist, Communication system

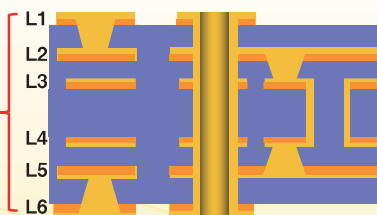


構造 Structure

- 異種材との複合構造にも対応

- Hybrid PWB

LowDk・Df 基材
LowDk・Df material



LowDk・Df 基材
LowDk・Df material

一般FR-4 基材
FR-4 general material

